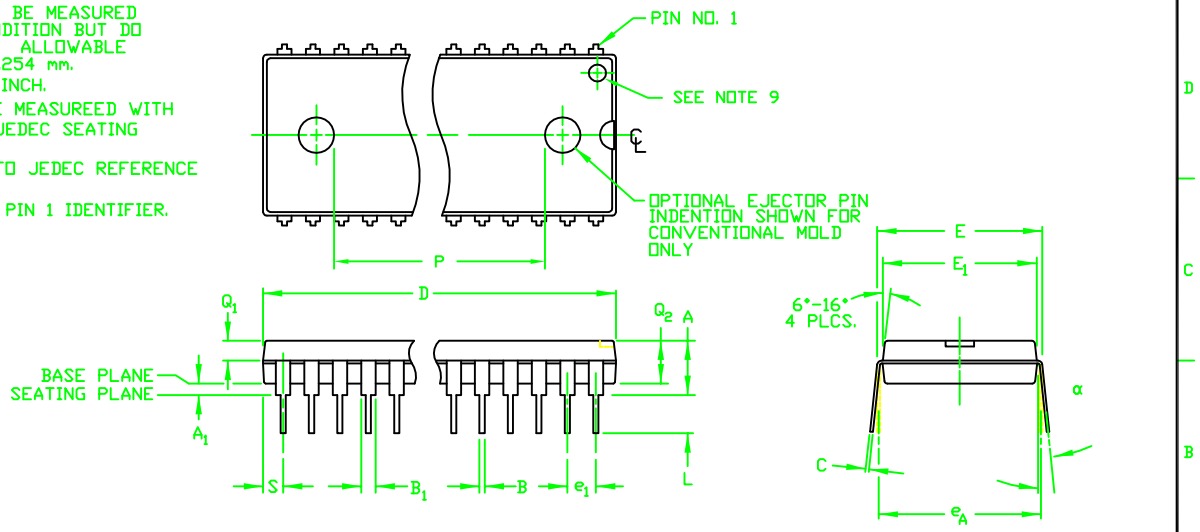
NOTES:

1. REFER TO APPLICABLE SYMBOL LIST.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1982.
3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
4. N IS THE MAXIMUM QUANTITY OF LEAD POSITIONS.
5. DIMENSION D & E_1 ARE TO BE MEASURED AT MAXIMUM MATERIAL CONDITION BUT DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS .010 INCH/.254 mm.
6. CONTROLLING DIMENSION: INCH.
7. DIMENSIONS A, A1 & L ARE MEASUREED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
8. THIS PACKAGE CONFORMS TO JEDEC REFERENCE MS-011, VARIATION AB.
9. IT IS AN OPTION TO SHOW PIN 1 IDENTIFIER.

REV.	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE.	8/5 1987	Y.M.K
01	INC. PER DCN #A30965.	8/27 1988	H.J.C
02	INC. PER DCN #A32104.	02/16 1990	H.J.C
03	INC. PER DCN #D21102.	02/28 1992	Y.M.K
04	INC. PER DCN #P50036.	05/20 1995	E.B.A.



DECIMAL ANGULAR XX± ±° XXX± XXXX±	PROJECTION	Anam Industrial Co., LTD. 151-22, Hwayang-Dong Sungdong-Ku, Seoul, Korea C.P.O. Box 1075	Amkor Electronics, Inc. 2423 Gateway Drive #200 Irving, Texas 75063 Excellence in semiconductor assembly
MATERIAL	APPROVALS / DATE: DRAWN K.MURRAY 7/8 1987; CHECKED J. DAVIS 7/8 1987; ENG'R M. BIRD 7/8 1987; RELEASED Y M KANG 8/5 1987	TITLE: PACKAGE OUTLINE, 28 LEAD, P-DIP, .600 INCH, FULL LEAD, AAWW	
FINISH		SIZE B; DWG. NO. 00286; REV. 04	
DO NOT SCALE DRAWING		SCALE 3/1	SHEET 1 OF 2